

Title (en)

Method of manufacturing base of electromagnetic relay.

Title (de)

Verfahren zur Herstellung der Grundplatte eines elektromagnetischen Relais.

Title (fr)

Méthode de fabrication d'un support de relais électromagnétique.

Publication

EP 0396098 A2 19901107 (EN)

Application

EP 90108259 A 19900430

Priority

JP 11322689 A 19890502

Abstract (en)

A method of manufacturing a base (3) of an electromagnetic relay, comprising the steps of: treating a surface of a resinous molded item (4) to a state enabling plating on the surface of the resinous molded item (4) such that the resinous molded item (4) has an upper terminal portion (5a), a lower terminal portion (5c) and a side terminal portion (5b) connecting the upper terminal portion (5a) and the lower terminal portion (5c); molding integrally with the resinous molded item (4), resin disabling plating thereon such that at least surfaces of the upper terminal portion (5a), the lower terminal portion (5c) and the side terminal portion (5b) are exposed outwardly; and plating an electrically conductive film on only the surfaces of the upper terminal portion (5a), the lower terminal portion (5c) and the side terminal portion (5b).

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